

THICK FILM DIGITAL attenuators DIODE OR RELAY SWITCHED • HERMETICALLY SEALED

T-71-11-01

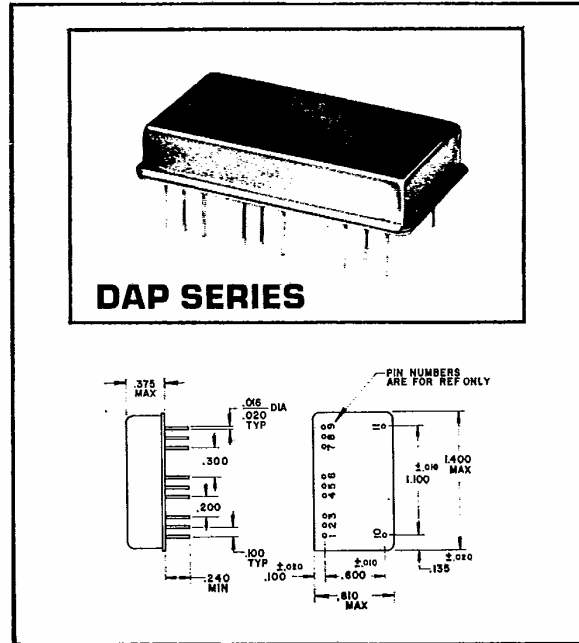
The "DAP" Series of digital attenuators utilize thick film techniques to achieve a high level of performance and reliability. Thick film Distributed Attenuators and circuit patterns are fired directly onto an alumina substrate at temperatures in excess of 800° C. Pin diodes are bonded to the substrate with blocking capacitors and RF chokes to form an integrated circuit. Laser trimming of each attenuator element assure precision accuracies.

GENERAL SPECIFICATIONS

Attenuation: 0-42dB in 6dB steps
 Characteristic Impedance: 50 Ω nominal
 Maximum RF Power: +20 dBm
 Switching Time: 1 MS maximum
 RF To Control Isolation: 60 dB minimum
 Operating Temperature Range: -54° C to +85° C
 Control Input: Positive Logic equals zero attenuation
 DC Control Signal: 1 VDC @ 10ma per BIT
 Material: Gold Plated Kovar
 Leads: Pretinned

P/N	Freq. Range	Atten. Step dB	Accuracy	Max. VSWR	Max. Insertion Loss
DAP1023	900-1200 MHz 24dB ± 1 dB	6, 12, 24	6dB ± .5 dB 12dB ± 1 dB	1.5:1	4.0 dB

NOTE: Other attenuation step sizes are available. Consult Factory.



HERMETIC PACKAGE

RELAY CELL attenuator THICK FILM

The "DAR" Series thick film attenuator cells are designed to be used with "add-on" microwave relays. Thick film Distributed Attenuators and circuit patterns are fired directly onto an alumina substrate at temperatures in excess of 800° C. Laser trimming of each attenuator element assure precision accuracies.

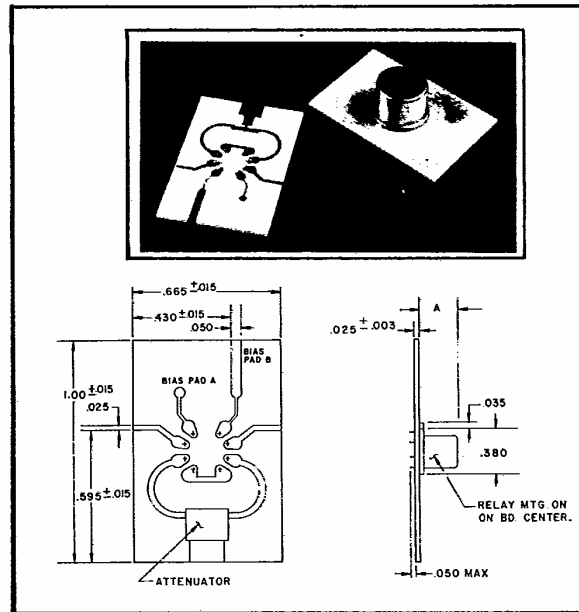
DAR SERIES

GENERAL SPECIFICATIONS

Attenuation: 0-20dB in 1dB steps
 Characteristic Impedance: 50 Ω nominal
 Maximum RF Power: +20 dBm
 Switching Time: 1 MS maximum
 RF To Control Isolation: 60 dB minimum
 Operating Temperature Range: -54° C to +85° C
 Control Input: Positive Logic equals zero attenuation
 DC Control Signal: 1 VDC @ 10ma per BIT
 Frequency Range: DC-2 GHz
 VSWR: 1.5:1 max.
 Insertion Loss: .75 dB max. per cell
 Accuracy: ±0.2 dB, 1-6 dB; ±.25 dB, 7-10 dB
 ±.5 dB, 11-20 dB

NOTE 1: Relay Cell Attenuators are available for various relay schematics; Consult factory for details.

- Relay Cell Attenuators are available with "On Board" TTL Driver Circuits.
- Special patterns of multiple cells on a single substrate are also available.



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THICK FILM DIGITAL attenuators SURFACE MOUNT/PLUG IN

The "DAC" Series of digital attenuators are thick film Microwave Integrated Circuits. Attenuator elements and conductor patterns are fired directly onto the alumina substrate. The attenuator pads are calibrated by laser techniques. PIN diodes, blocking capacitors and RF chokes are attached to the ceramic substrate.

GENERAL SPECIFICATIONS

Characteristic Impedance: 50 Ω nominal
 Maximum RF Power: 1.00 mw max.
 Switching Time: 200 ns maximum
 RF To Control Isolation: 60 dB maximum
 Operating Temperature Range: -55° C +125° C
 Logic Input: See performance table

MECHANICAL CHARACTERISTICS

The DAC family is available with either a plastic lid, a ceramic lid or as an uncased device. All are suitable for surface mounting and have tabs and pads for external connections. To specify package options, add the following suffix codes:

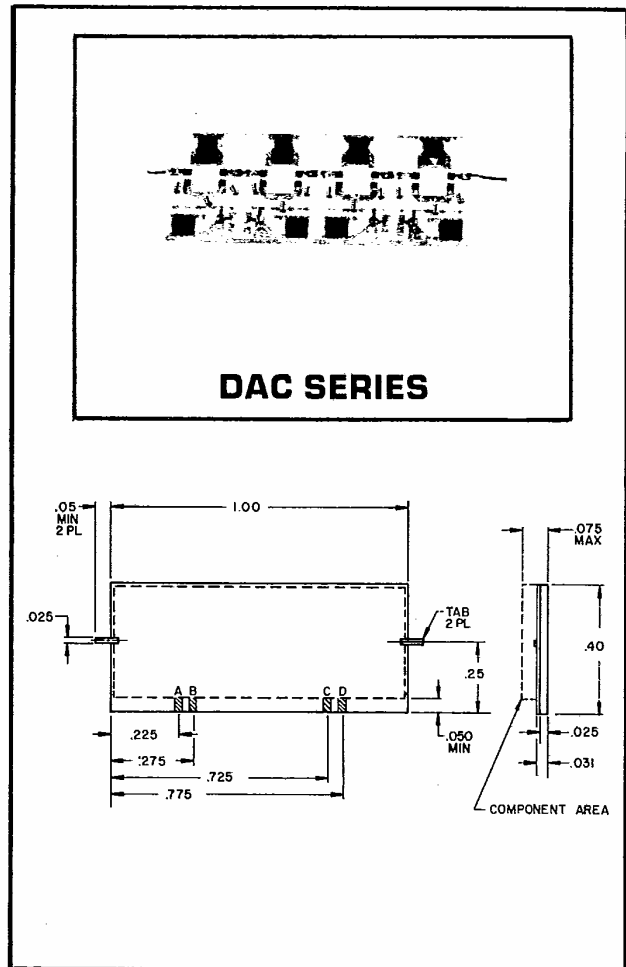
P = Plastic lid
 C = Ceramic lid

LOGIC INPUT

Positive logic equals zero attenuation path

Drive Current/per BIT: ± 25 ma/ ± 40 ma (see electrical performance table)

Maximum Compliance Voltage = ± 5 V



ELECTRICAL PERFORMANCE

P/N	Frequency Range	Attenuation Per BIT (dB)	Per BIT Accuracy	Maximum VSWR	Maximum Insertion Loss	Drive Current*
DAC2534-2	.250-3.5 GHz	16, 8, 4, 2	$\pm .75$ dB	1.5:1	3.2 dB	± 40 ma
DAC2534-1	.250-3.5 GHz	8, 4, 2, 1	$\pm .5$ dB	1.5:1	3.2 dB	± 40 ma

* per BIT

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